


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/10695	
1.3 Title of PCN	Capacity Extension for DPAK Mixed Wire Products in Tong Fu Microelectronics	
1.4 Product Category	Power MOSFET	
1.5 Issue date	2018-02-01	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Riccardo NICOLOSO
2.1.2 Marketing Manager	Antonino PELLEGRINO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Tong Fu Microelectronics

4. Description of change

	Old	New
4.1 Description	DPAK Mixed Wire products manufactured in ST's Shenzhen Plant	DPAK Mixed Wire products manufactured also in Tong Fu MicroElectronics Subcon based in China
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact in terms of electrical, physical and functional aspects	

5. Reason / motivation for change

5.1 Motivation	Capacity Extension and improvement in Flexibility to better manage the customer orders
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	by Q.A. number
------------------------	----------------

7. Timing / schedule

7.1 Date of qualification results	2018-01-23
7.2 Intended start of delivery	2018-04-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	10695 PCN - Capacity Extension for DPAK Mixed Wire to Tong Fu Microelectronics.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-02-01

9. Attachments (additional documentations)

10695 Public product.pdf
10695 PCN - Capacity Extension for DPAK Mixed Wire to Tong Fu Microelectronics.doc
10695 PCN - Capacity Extension for DPAK Mixed Wire to Tong Fu Microelectronics.pdf

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD10P10F6	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Capacity Extension for DPAK Mixed Wire Products in Tong Fu Microelectronics

PCN Reference : ADG/18/10695

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STD10P10F6		
------------	--	--



IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.